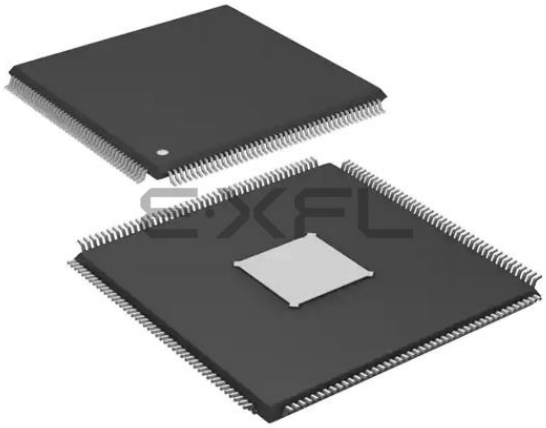

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Fixed/Floating Point
Interface	CAN, EBI/EMI, Ethernet, DAI, I²C, MMC/SD/SDIO, SPI, SPORT, UART/USART, USB OTG
Clock Rate	450MHz, 450MHz
Non-Volatile Memory	External
On-Chip RAM	1.768MB
Voltage - I/O	3.30V
Voltage - Core	1.10V
Operating Temperature	-40°C ~ 100°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP Exposed Pad
Supplier Device Package	176-LQFP-EP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/adsp-sc571cswz-4

The system configuration is flexible, but a typical configuration is 512 Kb DM, 128 Kb PM, and 128 Kb of instruction cache, with the remaining L1 memory configured as SRAM. Each addressable memory space outside the L1 memory can be accessed either directly or via cache.

The memory map in Table 4 gives the L1 memory address space and shows multiple L1 memory blocks offering a configurable mix of SRAM and cache.

L1 Master and Slave Ports

Each SHARC+ core has two master ports and two slave ports to and from the system fabric. One master port fetches instructions. The second master port drives data to the system world. Slave port 1 together with slave port 2 (MDMA) run conflict free access to the individual memory blocks. For the slave port address, refer to the L1 memory address map in Table 4.

L1 On-Chip Memory Bandwidth

The internal memory architecture allows programs to have four accesses at the same time to any of the four blocks, assuming no block conflicts. The total bandwidth is realized using both the DMD and PMD buses (2 × 64-bits CCLK speed and 2 × 32-bit SYSCLK speed).

Instruction and Data Cache

The ADSP-SC57x/ADSP-2157x processors also include a traditional instruction cache (I-cache) and two data caches (D-cache) (PM/DM caches) with parity support for all caches. These caches support one instruction access and two data accesses over the DM and PM buses, per CCLK cycle. The cache controllers automatically manage the configured L1 memory. The system can configure part of the L1 memory for automatic management by the cache controllers. The sizes of these caches are independently configurable from 0 kB to a maximum of 128 kB each. The memory not managed by the cache controllers is directly addressable by the processors. The controllers ensure the data coherence between the two data caches. The caches provide user-controllable features such as full and partial locking, range bound invalidation, and flushing.

System Event Controller (SEC) Input

The output of the system event controller (SEC) controller is forwarded to the core event controller (CEC) to respond directly to all unmasked system-based interrupts. The SEC also supports nesting including various SEC interrupt channel arbitration options. The processor automatically stacks the arithmetic status (ASTATx and ASTATy) registers and mode (MODE1) register in parallel with the interrupt servicing for all SEC channels.

Core Memory-Mapped Registers (CMMR)

The core memory-mapped registers (CMMR) control the L1 instruction and data cache, BTB, L2 cache, parity error, system control, debug, and monitor functions.

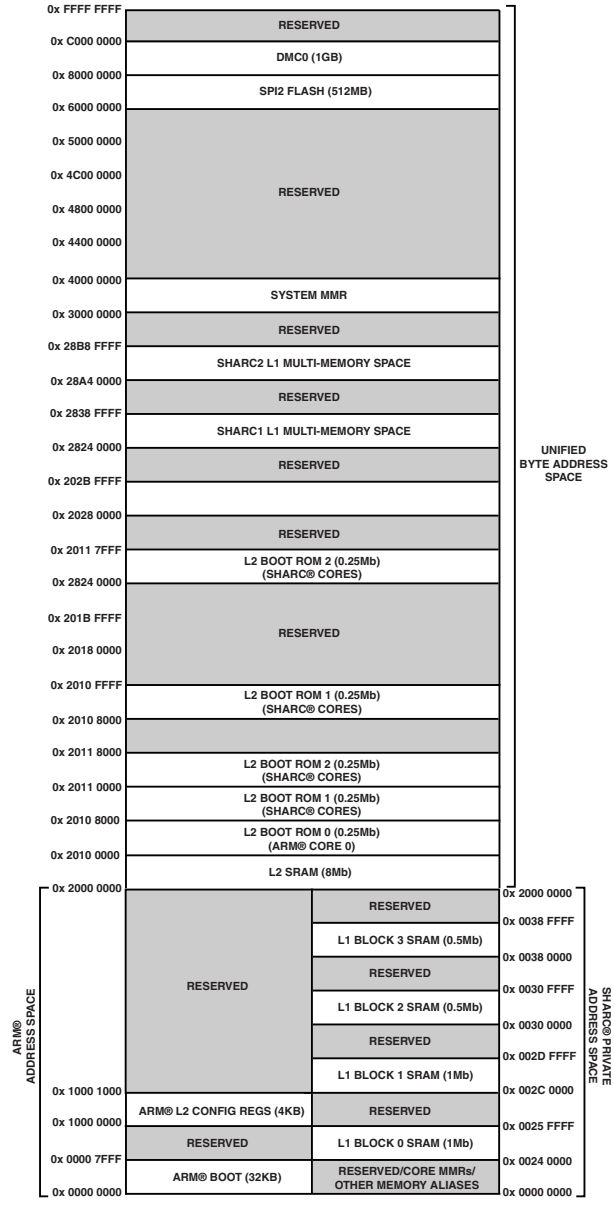

Figure 5. ADSP-SC57x/ADSP-2157x Memory Map

SHARC+ CORE ARCHITECTURE

The ADSP-SC57x/ADSP-2157x processors are code compatible at the assembly level with the ADSP-2148x, ADSP-2147x, ADSP-2146x, ADSP-2137x, ADSP-2136x, ADSP-2126x, ADSP-2116x, and with the first-generation ADSP-2106x SHARC processors.

The ADSP-SC57x/ADSP-2157x processors share architectural features with the ADSP-2126x, ADSP-2136x, ADSP-2137x, ADSP-214xx, and ADSP-2116x SIMD SHARC processors, shown in Figure 4 and detailed in the following sections.

The two capacitors and the series resistor, shown in Figure 6, fine tune phase and amplitude of the sine frequency. The capacitor and resistor values shown in Figure 6 are typical values only. The capacitor values are dependent upon the load capacitance recommendations of the crystal manufacturer and the physical layout of the printed circuit board (PCB). The resistor value depends on the drive level specified by the crystal manufacturer. The user must verify the customized values based on careful investigations on multiple devices over the required temperature range.

A third overtone crystal can be used for frequencies above 25 MHz. The circuit is then modified to ensure crystal operation only at the third overtone by adding a tuned inductor circuit, shown in Figure 6. A design procedure for third overtone operation is discussed in detail in "Using Third Overtone Crystals with the ADSP-218x DSP" (EE-168). The same recommendations can be used for the USB crystal oscillator.

Clock Distribution Unit (CDU)

The two CGUs each provide outputs which feed a clock distribution unit (CDU). The clock outputs CLKO0–CLKO9 are connected to various targets. For more information, refer to the ADSP-SC57x/ADSP-2157x SHARC+ Processor Hardware Reference.

Power-Up

SYS_XTALx oscillations (SYS_CLKINx) start when power is applied to the VDD_EXT pins. The rising edge of $\overline{\text{SYS\_HWRST}}$ starts on-chip PLL locking (PLL lock counter). The deassertion must apply only if all voltage supplies and SYS_CLKINx oscillations are valid (refer to the Power-Up Reset Timing section).

Clock Out/External Clock

The SYS_CLKOUT output pin has programmable options to output divided-down versions of the on-chip clocks. By default, the SYS_CLKOUT pin drives a buffered version of the SYS_ CLKIN0 input. Refer to the ADSP-SC57x/ADSP-2157x SHARC+ Processor Hardware Reference to change the default mapping of clocks.

Booting

The processors have several mechanisms for automatically loading internal and external memory after a reset. The boot mode is defined by the SYS_BMODE[n] input pins. There are two categories of boot modes. In master boot mode, the processors actively load data from serial memories. In slave boot modes, the processors receive data from external host devices.

The boot modes are shown in Table 9. These modes are implemented by the SYS_BMODE[n] bits of the reset configuration register and are sampled during power-on resets and software initiated resets.

In the ADSP-SC57x processors, the ARM Cortex-A5 (Core 0) controls the boot process, including loading all internal and external memory. Likewise, in the ADSP-2157x processors, the SHARC+ (Core 1) controls the boot function. The option for secure boot is available on all models.

Table 9. Boot Modes

SYS_BMODE[n] Setting[1, 2]	Boot Mode
000	No boot
001	SPI2 master
010	SPI2 slave
011	UART0 slave
100	Reserved
101	Reserved
110	Link0 slave

[1] SYS_BMODE2 pin is applicable only for the BGA package.
[2] Link0 slave boot is supported only on the BGA package.

Thermal Monitoring Unit (TMU)

The thermal monitoring unit (TMU) provides on-chip temperature measurement for applications that require substantial power consumption. The TMU is integrated into the processor die and digital infrastructure using an MMR-based system access to measure the die temperature variations in real-time.

TMU features include the following:

- On-chip temperature sensing
- Programmable over temperature and under temperature limits
- Programmable conversion rate
- Programmable clock source selection to run the sensor off an independent local clock
- Averaging feature available

Power Supplies

The processors have separate power supply connections for

- Internal (VDD_INT)
- External (VDD_EXT)
- USB (VDD_USB)
- HADC/TMU (VDD_HADC)
- DMC (VDD_DMC)

All power supplies must meet the specifications provided in Operating Conditions section. All external supply pins must be connected to the same power supply.

Power Management

As shown in Table 10, the processors support four different power domains, which maximizes flexibility while maintaining compliance with industry standards and conventions. There are no sequencing requirements for the various power domains, but all domains must be powered according to the appropriate specifications (see the Specifications section for processor operating conditions). If the feature or the peripheral is not used, refer to Table 25.

ADSP-SC57x/ADSP-2157x DETAILED SIGNAL DESCRIPTIONS

Table 11 provides a detailed description of each pin.

Table 11. ADSP-SC57x/ADSP-2157x Detailed Signal Descriptions

Signal Name	Direction	Description
ACM_A[n]	Output	**ADC Control Signals.** Function varies by mode.
ACM_T[n]	Input	**External Trigger n.** Input for external trigger events.
C1_FLG[n]	Output	**SHARC Core 1 Flag Pin.**
C2_FLG[n]	Output	**SHARC Core 2 Flag Pin.**
CAN_RX	Input	**Receive.** Typically an external CAN transceiver RX output.
CAN_TX	Output	**Transmit.** Typically an external CAN transceiver TX input.
CNT_DG	Input	**Count Down and Gate.** Depending on the mode of operation, this input acts either as a count down signal or a gate signal. Count down—this input causes the GP counter to decrement. Gate—stops the GP counter from incrementing or decrementing.
CNT_UD	Input	**Count Up and Direction.** Depending on the mode of operation, this input acts either as a count up signal or a direction signal. Count up—this input causes the GP counter to increment. Direction—selects whether the GP counter is incrementing or decrementing.
CNT_ZM	Input	**Count Zero Marker.** Input that connects to the zero marker output of a rotary device or detects the pressing of a pushbutton.
DAI_PIN[nn]	InOut	**Pin n.** The digital applications interface (DAI0) connects various peripherals to any of the DAI0_PINxx pins. Programs make these connections using the signal routing unit (SRU).
DMC_A[nn]	Output	**Address n.** Address bus.
DMC_BA[n]	Output	**Bank Address n.** Defines which internal bank an activate, read, write or precharge command is applied to on the dynamic memory. Bank Address n also defines which mode registers (MR, EMR, EMR2, and/or EMR3) load during the load mode register command.
$\overline{\text{DMC\_CAS}}$	Output	**Column Address Strobe.** Defines the operation for external dynamic memory to perform in conjunction with other DMC command signals. Connect to the CAS input of dynamic memory.
DMC_CK	Output	**Clock.** Outputs DCLK to external dynamic memory.
$\overline{\text{DMC\_CK}}$	Output	**Clock (Complement).** Complement of DMC_CK.
DMC_CKE	Output	**Clock Enable.** Active high clock enables. Connects to the CKE input of the dynamic memory.
$\overline{\text{DMC\_CS[n]}}$	Output	**Chip Select n.** Commands are recognized by the memory only when this signal is asserted.
DMC_DQ[nn]	InOut	**Data n.** Bidirectional data bus.
DMC_LDM	Output	**Data Mask for Lower Byte.** Mask for DMC_DQ07:DMC_DQ00 write data when driven high. Sampled on both edges of the data strobe by the dynamic memory.
DMC_LDQS	InOut	**Data Strobe for Lower Byte.** DMC_DQ07:DMC_DQ00 data strobe. Output with write data. Input with read data. Can be single-ended or differential depending on register settings.
$\overline{\text{DMC\_LDQS}}$	InOut	**Data Strobe for Lower Byte (Complement).** Complement of DMC_LDQS. Not used in single-ended mode.
DMC_ODT	Output	**On Die Termination.** Enables dynamic memory termination resistances when driven high (assuming the memory is properly configured). ODT is enabled or disabled regardless of read or write commands.
$\overline{\text{DMC\_RAS}}$	Output	**Row Address Strobe.** Defines the operation for external dynamic memory to perform in conjunction with other DMC command signals. Connect to the RAS input of dynamic memory.
$\overline{\text{DMC\_RESET}}$	Output	**Reset (DDR3 Only).**
DMC_RZQ	InOut	**External Calibration Resistor Connection.**
DMC_UDM	Output	**Data Mask for Upper Byte.** Mask for DMC_DQ15:DMC_DQ08 write data when driven high. Sampled on both edges of the data strobe by the dynamic memory.
DMC_UDQS	InOut	**Data Strobe for Upper Byte.** DMC_DQ15:DMC_DQ08 data strobe. Output with write data. Input with read data. Can be single-ended or differential depending on register settings.

Table 17. Signal Multiplexing for Port E (Continued)

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PE_03	LP0_ACK				
PE_04	LP0_D0				
PE_05	LP0_D1				
PE_06	LP0_D2				
PE_07	LP0_D3				
PE_08	LP0_D4				
PE_09	LP0_D5				
PE_10	LP0_D6				
PE_11	LP0_D7				
PE_12	MSI0_D0		TM0_TMR0		
PE_13	MSI0_D1	C1_FLG0	CNT0_UD		
PE_14	MSI0_D2	$\overline{\text{UART1\_CTS}}$	TM0_TMR6		
PE_15	MSI0_D3	C2_FLG3			

Table 18. Signal Multiplexing for Port F

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PF_00	MSI0_D4	TRACE0_D00			
PF_01	MSI0_D5	TRACE0_D01			
PF_02	MSI0_D6	TRACE0_D02			
PF_03	MSI0_D7	TRACE0_D03			
PF_04	MSI0_CLK	C1_FLG2	$\overline{\text{SPI0\_SEL6}}$		
PF_05	ETH0_PTPCLKIN0	TM0_TMR1	$\overline{\text{SPI0\_SEL5}}$		
PF_06	ETH0_PTPAUXIN2	TRACE0_CLK			TM0_ACLK1
PF_07	ETH0_PTPAUXIN3	TM0_TMR2	MSI0_CMD		
PF_08	$\overline{\text{UART0\_TX}}$				
PF_09	$\overline{\text{UART0\_RX}}$				TM0_ACI0
PF_10	$\overline{\text{UART1\_TX}}$	$\overline{\text{SPI2\_SEL2}}$			
PF_11	$\overline{\text{UART1\_RX}}$	ACM0_A0	$\overline{\text{SPI1\_SEL3}}$	C2_FLG2	TM0_ACI1

Table 19 shows the internal timer signal routing. This table applies to both the 400-ball CSP_BGA and 176-lead LQFP packages.

Table 19. Internal Timer Signal Routing

Timer Input Signal	Internal Source
TM0_ACLK0[1]	SYS_CLKIN1
TM0_ACI5	DAI0_PB04_O
TM0_ACLK5	DAI0_PB03_O
TM0_ACI6	DAI0_PB20_O
TM0_ACLK6	DAI0_PB19_O
TM0_ACI7	CNT0_TO
TM0_ACLK7	SYS_CLKIN0

[1] Not applicable for LQFP package.

Table 20. ADSP-SC57x/ADSP-2157x 176-Lead LQFP Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
LP1_D7	LP1 Data 7	D	PD_09
MLB0_CLK	MLB0 Single-Ended Clock	B	PB_06
MLB0_CLKOUT	MLB0 Single-Ended Clock Out	B	PB_03
MLB0_DAT	MLB0 Single-Ended Data	B	PB_04
MLB0_SIG	MLB0 Single-Ended Signal	B	PB_05
PPI0_CLK	EPPI0 Clock	C	PC_11
PPI0_D00	EPPI0 Data 0	D	PD_10
PPI0_D01	EPPI0 Data 1	D	PD_11
PPI0_D02	EPPI0 Data 2	D	PD_12
PPI0_D03	EPPI0 Data 3	D	PD_13
PPI0_D04	EPPI0 Data 4	D	PD_14
PPI0_D05	EPPI0 Data 5	D	PD_15
PPI0_D06	EPPI0 Data 6	C	PC_05
PPI0_D07	EPPI0 Data 7	D	PD_09
PPI0_D08	EPPI0 Data 8	C	PC_01
PPI0_D09	EPPI0 Data 9	C	PC_02
PPI0_D10	EPPI0 Data 10	C	PC_03
PPI0_D11	EPPI0 Data 11	C	PC_04
PPI0_FS1	EPPI0 Frame Sync 1 (HSYNC)	C	PC_14
PPI0_FS2	EPPI0 Frame Sync 2 (VSYNC)	C	PC_15
PPI0_FS3	EPPI0 Frame Sync 3 (FIELD)	C	PC_06
SPI0_CLK	SPI0 Clock	C	PC_01
SPI0_MISO	SPI0 Master In, Slave Out	C	PC_02
SPI0_MOSI	SPI0 Master Out, Slave In	C	PC_03
SPI0_RDY	SPI0 Ready	C	PC_05
$\overline{\text{SPI0\_SEL1}}$	SPI0 Slave Select Output 1	C	PC_04
$\overline{\text{SPI0\_SEL2}}$	SPI0 Slave Select Output 2	C	PC_05
$\overline{\text{SPI0\_SEL3}}$	SPI0 Slave Select Output 3	C	PC_06
$\overline{\text{SPI0\_SEL4}}$	SPI0 Slave Select Output 4	A	PA_09
$\overline{\text{SPI0\_SEL5}}$	SPI0 Slave Select Output 5	D	PD_03
$\overline{\text{SPI0\_SEL6}}$	SPI0 Slave Select Output 6	D	PD_04
$\overline{\text{SPI0\_SEL7}}$	SPI0 Slave Select Output 7	D	PD_05
$\overline{\text{SPI0\_SS}}$	SPI0 Slave Select Input	C	PC_04
SPI1_CLK	SPI1 Clock	C	PC_07
SPI1_MISO	SPI1 Master In, Slave Out	C	PC_08
SPI1_MOSI	SPI1 Master Out, Slave In	C	PC_09
SPI1_RDY	SPI1 Ready	C	PC_11
$\overline{\text{SPI1\_SEL1}}$	SPI1 Slave Select Output 1	C	PC_10
$\overline{\text{SPI1\_SEL2}}$	SPI1 Slave Select Output 2	C	PC_11
$\overline{\text{SPI1\_SEL3}}$	SPI1 Slave Select Output 3	A	PA_08
$\overline{\text{SPI1\_SEL4}}$	SPI1 Slave Select Output 4	A	PA_14
$\overline{\text{SPI1\_SEL5}}$	SPI1 Slave Select Output 5	B	PB_02
$\overline{\text{SPI1\_SEL6}}$	SPI1 Slave Select Output 6	D	PD_07
$\overline{\text{SPI1\_SEL7}}$	SPI1 Slave Select Output 7	D	PD_06
$\overline{\text{SPI1\_SS}}$	SPI1 Slave Select Input	C	PC_10
SPI2_CLK	SPI2 Clock	B	PB_14
SPI2_D2	SPI2 Data 2	B	PB_12
SPI2_D3	SPI2 Data 3	B	PB_13

Table 25. ADSP-SC57x/ADSP-2157x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Internal Termination	Reset Drive	Power Domain	Description and Notes
$\overline{\text{DMC0\_CAS}}$	Output	B	none	L	VDD_DMC	Desc: DMC0 Column Address Strobe Notes: No notes
DMC0_CK	Output	C	none	L	VDD_DMC	Desc: DMC0 Clock Notes: No notes
DMC0_CKE	Output	B	none	L	VDD_DMC	Desc: DMC0 Clock enable Notes: No notes
$\overline{\text{DMC0\_CK}}$	Output	C	none	L	VDD_DMC	Desc: DMC0 Clock (complement) Notes: No notes
$\overline{\text{DMC0\_CS0}}$	Output	B	none	L	VDD_DMC	Desc: DMC0 Chip Select 0 Notes: No notes
DMC0_DQ00	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 0 Notes: No notes
DMC0_DQ01	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 1 Notes: No notes
DMC0_DQ02	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 2 Notes: No notes
DMC0_DQ03	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 3 Notes: No notes
DMC0_DQ04	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 4 Notes: No notes
DMC0_DQ05	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 5 Notes: No notes
DMC0_DQ06	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 6 Notes: No notes
DMC0_DQ07	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 7 Notes: No notes
DMC0_DQ08	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 8 Notes: No notes
DMC0_DQ09	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 9 Notes: No notes
DMC0_DQ10	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 10 Notes: No notes
DMC0_DQ11	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 11 Notes: No notes
DMC0_DQ12	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 12 Notes: No notes
DMC0_DQ13	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 13 Notes: No notes
DMC0_DQ14	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 14 Notes: No notes
DMC0_DQ15	InOut	B	none	none	VDD_DMC	Desc: DMC0 Data 15 Notes: No notes
DMC0_LDM	Output	B	none	L	VDD_DMC	Desc: DMC0 Data Mask for Lower Byte Notes: No notes
DMC0_LDQS	InOut	C	none	none	VDD_DMC	Desc: DMC0 Data Strobe for Lower Byte Notes: External weak pull-down required in LPDDR mode

Table 25. ADSP-SC57x/ADSP-2157x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Internal Termination	Reset Drive	Power Domain	Description and Notes
DMC0_LDQS	InOut	C	none	none	VDD_DMC	Desc: DMC0 Data Strobe for Lower Byte (complement) Notes: No notes
DMC0_ODT	Output	B	none	L	VDD_DMC	Desc: DMC0 On-die termination Notes: No notes
DMC0_RAS	Output	B	none	L	VDD_DMC	Desc: DMC0 Row Address Strobe Notes: No notes
DMC0_RESET	Output	B	none	L	VDD_DMC	Desc: DMC0 Reset (DDR3 only) Notes: No notes
DMC0_RZQ	a	B	none	none	VDD_DMC	Desc: DMC0 External calibration resistor connection Notes: Applicable for DDR2 and DDR3 only. Pull down using a 34 Ohm resistor.
DMC0_UDM	Output	B	none	L	VDD_DMC	Desc: DMC0 Data Mask for Upper Byte Notes: No notes
DMC0_UDQS	InOut	C	none	none	VDD_DMC	Desc: DMC0 Data Strobe for Upper Byte Notes: External weak pull-down required in LPDDR mode
DMC0_UDQS	InOut	C	none	none	VDD_DMC	Desc: DMC0 Data Strobe for Upper Byte (complement) Notes: No notes
DMC0_VREF	a		none	none	VDD_DMC	Desc: DMC0 Voltage Reference Notes: No notes
DMC0_WE	Output	B	none	L	VDD_DMC	Desc: DMC0 Write Enable Notes: No notes
GND	g		none	none		Desc: Ground Notes: No notes
HADC0_VIN0	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 0 Notes: Connect to GND through a resistor if not used[4]
HADC0_VIN1	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 1 Notes: Connect to GND through a resistor if not used[4]
HADC0_VIN2	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 2 Notes: Connect to GND through a resistor if not used[4]
HADC0_VIN3	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 3 Notes: Connect to GND through a resistor if not used[4]
HADC0_VIN4	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 4 Notes: Connect to GND through a resistor if not used[4]
HADC0_VIN5	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 5 Notes: Connect to GND through a resistor if not used[4]
HADC0_VIN6	a	NA	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 6 Notes: Connect to GND through a resistor if not used[4]

Table 25. ADSP-SC57x/ADSP-2157x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Internal Termination	Reset Drive	Power Domain	Description and Notes
PB_10	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 10 Notes: Connect to VDD_EXT or GND if not used
PB_11	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 11 Notes: Connect to VDD_EXT or GND if not used
PB_12	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 12 Notes: Connect to VDD_EXT or GND if not used
PB_13	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 13 Notes: Connect to VDD_EXT or GND if not used
PB_14	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 14 Notes: Connect to VDD_EXT or GND if not used
PB_15	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTB Position 15 Notes: See note[2]
PC_00	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 0 Notes: See note[2]
PC_01	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 1 Notes: See note[2]
PC_02	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 2 Notes: See note[2]
PC_03	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 3 Notes: See note[2]
PC_04	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 4 Notes: See note[2]
PC_05	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 5 Notes: See note[2]
PC_06	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 6 Notes: See note[2]
PC_07	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 7 Notes: See note[2]
PC_08	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 8 Notes: See note[2]
PC_09	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 9 Notes: See note[2]
PC_10	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 10 Notes: See note[2]
PC_11	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 11 Notes: See note[2]
PC_12	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 12 Notes: See note[2]
PC_13	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 13 Notes: See note[2]
PC_14	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 14 Notes: See note[2]
PC_15	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 15 Notes: See note[2]

DDR3 SDRAM Read Cycle Timing

Table 50 and Figure 17 show mobile DDR3 SDRAM read cycle timing, related to the DMC.

Table 50. DDR3 SDRAM Read Cycle Timing, V_{DD_DMC} Nominal 1.5 V

Parameter		450 MHz[1]		Unit
		Min	Max	
Timing Requirements				
t_{DQSQ}	DMC0_DQS to DMC0_DQ Skew for DMC0_DQS and Associated DMC0_DQ Signals		0.15	ns
t_{QH}	DMC0_DQ, DMC0_DQS Output Hold Time From DMC0_DQS	0.38		t_{CK}
t_{RPRE}	Read Preamble	0.9		t_{CK}
t_{RPST}	Read Postamble	0.3		t_{CK}

[1] To ensure proper operation of the DDR3, all the DDR3 requirements must be strictly followed. See "Interfacing DDR3/DDR2/LPDDR Memory to ADSP-SC5xx/215xx Processors" (EE-387).

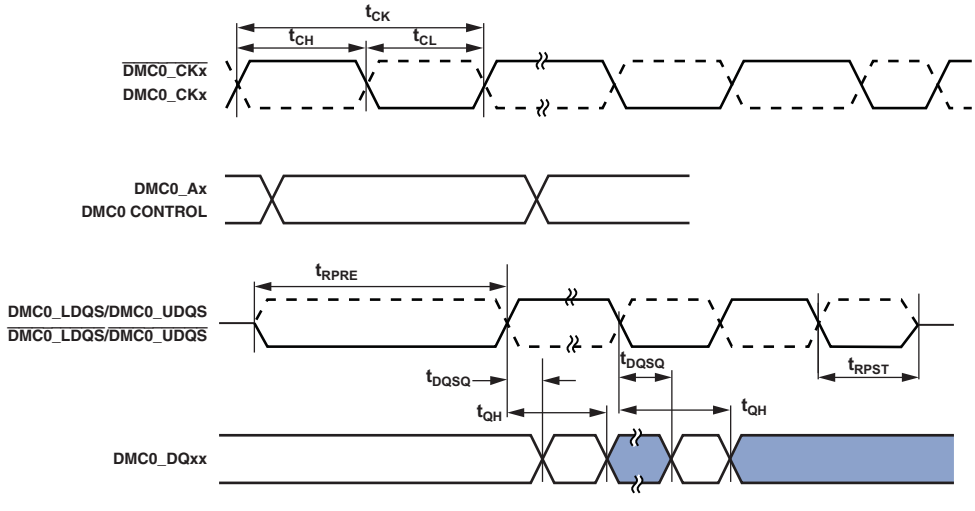

Figure 17. DDR3 SDRAM Controller Input AC Timing

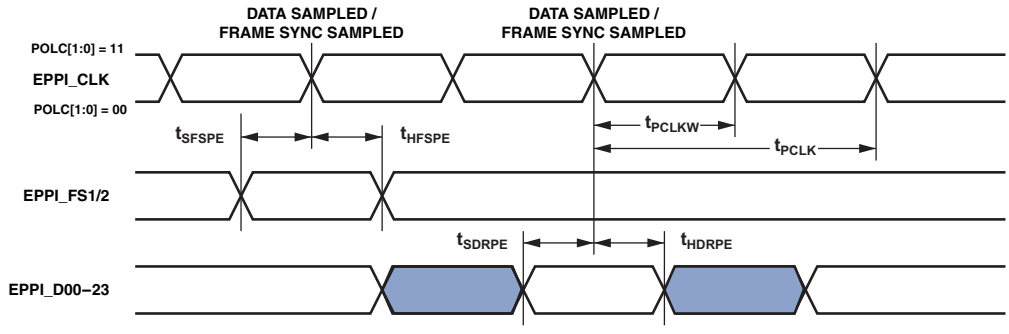

Figure 26. EPPI External Clock GP Receive Mode with External Frame Sync Timing

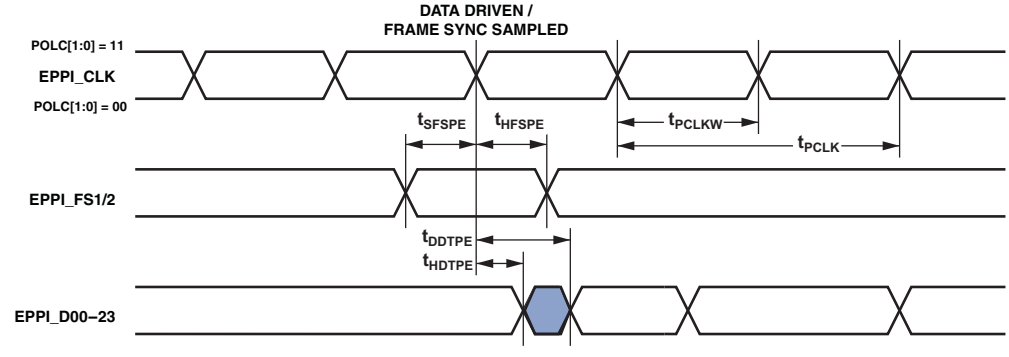

Figure 27. EPPI External Clock GP Transmit Mode with External Frame Sync Timing

Table 60. SPORTs—External Late Frame Sync[1]

Parameter		Min	Max	Unit
Switching Characteristics				
$t_{DDTLFSE}$	Data Delay from Late External Transmit Frame Sync or External Receive Frame Sync with MCE = 1, MFD = 0[2]		14	ns
$t_{DDTENFS}$	Data Enable for MCE = 1, MFD = 0[2]	0.5		ns

[1] Specifications apply to all four SPORTs.
[2] The $t_{DDTLFSE}$ and $t_{DDTENFS}$ parameters apply to left justified as well as standard serial mode and MCE = 1, MFD = 0.

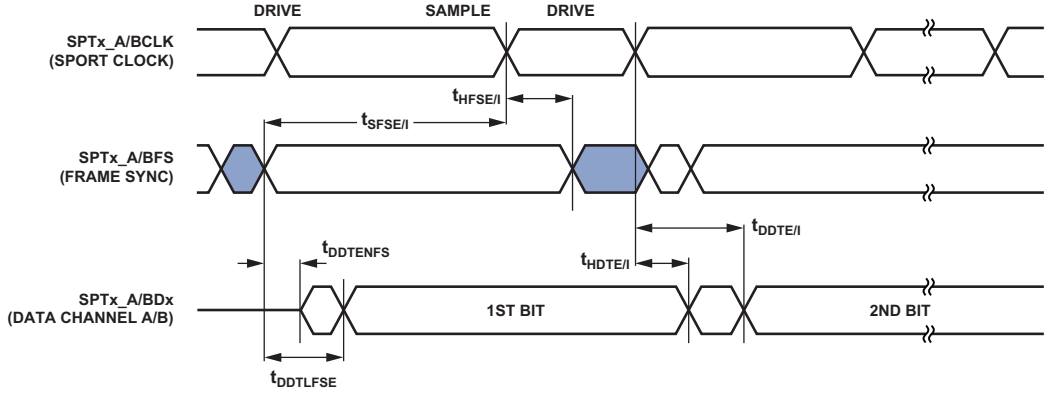

Figure 33. External Late Frame Sync

Asynchronous Sample Rate Converter (ASRC)—Serial Input Port

The ASRC input signals are routed from the DAI0_PINx pins using the SRU. Therefore, the timing specifications provided in Table 61 are valid at the DAI0_PINx pins.

Table 61. ASRC, Serial Input Port

Parameter		Min	Max	Unit
Timing Requirements				
t_{SRCSFS}[1]	Frame Sync Setup Before Serial Clock Rising Edge	4		ns
t_{SRCHFS}[1]	Frame Sync Hold After Serial Clock Rising Edge	5.5		ns
t_{SRCSD}[1]	Data Setup Before Serial Clock Rising Edge	4		ns
t_{SRCHD}[1]	Data Hold After Serial Clock Rising Edge	5.5		ns
$t_{SRCCLKW}$	Clock Width	$t_{SCLK0} - 1$		ns
t_{SRCCLK}	Clock Period	$2 \times t_{SCLK0}$		ns

[1] The serial clock, data, and frame sync signals can come from any of the DAI pins. The serial clock and frame sync signals can also come via PCG or SPORTs. The input of the PCG can be either CLKIN or any of the DAI pins.

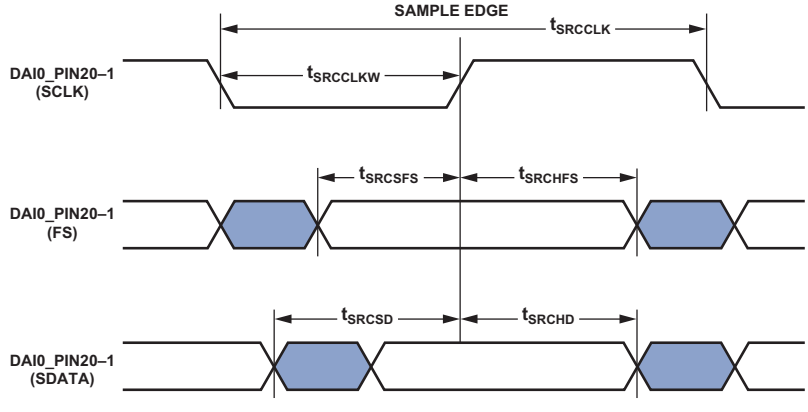

Figure 34. ASRC Serial Input Port Timing

SPI Port—Slave Timing

SPI0, SPI1, and SPI2

Table 65, Table 66, and Figure 37 describe SPI port slave operations. Note that

- In dual-mode data transmit, the SPIx_MOSI signal is also an output.
- In quad-mode data transmit, the SPIx_MOSI, SPIx_D2, and SPIx_D3 signals are also outputs.
- In dual-mode data receive, the SPIx_MISO signal is also an input.
- In quad-mode data receive, the SPIx_MISO, SPIx_D2, and SPIx_D3 signals are also inputs.
- In SPI slave mode, the SPI clock is supplied externally and is called $f_{SPICLKEXT}$:

$$t_{SPICLKEXT} = \frac{1}{f_{SPICLKEXT}}$$

- Quad mode is supported by SPI2 only.
- CPHA is a configuration bit in the SPI_CTL register.

Table 65. SPI0, SPI1 Port—Slave Timing[1]

Parameter		Min	Max	Unit
Timing Requirements				
t_{SPICHS}	SPIx_CLK High Period[2]	$0.5 \times t_{SPICLKEXT} - 1.5$		ns
t_{SPICLS}	SPIx_CLK Low Period[2]	$0.5 \times t_{SPICLKEXT} - 1.5$		ns
t_{SPICLK}	SPIx_CLK Period[2]	$t_{SPICLKEXT} - 1.5$		ns
t_{HDS}	Last SPIx_CLK Edge to $\overline{\text{SPIx\_SS}}$ Not Asserted	5		ns
t_{SPITDS}	Sequential Transfer Delay	$t_{SPICLKEXT} - 1.5$		ns
t_{SDSCI}	$\overline{\text{SPIx\_SS}}$ Assertion to First SPIx_CLK Edge	11.7		ns
t_{SSPID}	Data Input Valid to SPIx_CLK Edge (Data Input Setup)	2		ns
t_{HSPID}	SPIx_CLK Sampling Edge to Data Input Invalid	1.6		ns
Switching Characteristics				
t_{DSOE}	$\overline{\text{SPIx\_SS}}$ Assertion to Data Out Active	0	14.12	ns
t_{DSDHI}	$\overline{\text{SPIx\_SS}}$ Deassertion to Data High Impedance	0	12.6	ns
t_{DDSPID}	SPIx_CLK Edge to Data Out Valid (Data Out Delay)		14.16	ns
t_{HDSPID}	SPIx_CLK Edge to Data Out Invalid (Data Out Hold)	1.5		ns

[1] All specifications apply to SPI0 and SPI1.
[2] This specification indicates the minimum instantaneous width or period that can be tolerated due to duty cycle variation or jitter on the external SPIx_CLK. For the external SPIx_CLK ideal maximum frequency, see the $f_{SPICLKTEXT}$ specification in Table 27.

SPI Port—SPIx_RDY Master Timing

SPIx_RDY is used to provide flow control. CPOL and CPHA are configuration bits in the SPIx_CTL register, while LEADX, LAGX, and STOP are configuration bits in the SPIx_DLY register.

Table 70. SPI Port—SPIx_RDY Master Timing[1]

Parameter		Conditions	Min	Max	Unit
Timing Requirement					
$t_{SRDYSCKM}$	Setup Time for SPIx_RDY Deassertion Before Last Valid Data SPIx_CLK Edge		$(2 + 2 \times BAUD^{2}) \times t_{SCLK1} + 10$		ns
Switching Characteristic					
$t_{DRDYSCKM}$[3]	Assertion of SPIx_RDY to First SPIx_CLK Edge of Next Transfer	BAUD = 0, CPHA = 0	$4.5 \times t_{SCLK1}$	$5.5 \times t_{SCLK1} + 10$	ns
		BAUD = 0, CPHA = 1	$4 \times t_{SCLK1}$	$5 \times t_{SCLK1} + 10$	ns
		BAUD > 0, CPHA = 0	$(1 + 1.5 \times BAUD^{2}) \times t_{SCLK1}$	$(2 + 2.5 \times BAUD^{2}) \times t_{SCLK1} + 10$	ns
		BAUD > 0, CPHA = 1	$(1 + 1 \times BAUD^{2}) \times t_{SCLK1}$	$(2 + 2 \times BAUD^{2}) \times t_{SCLK1} + 10$	ns

[1] All specifications apply to all three SPIs.
[2] BAUD value is set using the SPIx_CLK.BAUD bits. BAUD value = SPIx_CLK.BAUD bits + 1.
[3] Specification assumes the LEADX, LAGX, and STOP bits in the SPI_DLY register are zero.

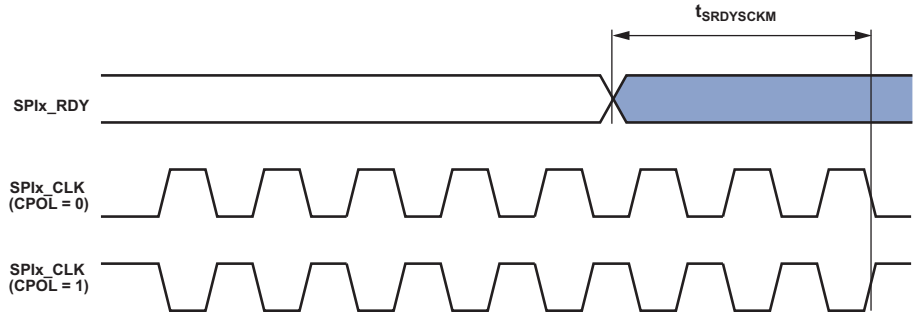

Figure 41. SPIx_RDY Setup Before SPIx_CLK

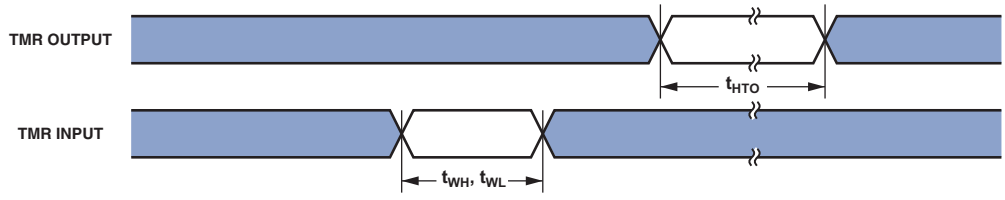

Figure 45. Timer Cycle Timing

DAI0 Pin to DAI0 Pin Direct Routing

Table 75 and Figure 46 describe I/O timing related to the DAI for direct pin connections only (for example, DAI0_PB01_I to DAI0_PB02_O).

Table 75. DAI Pin to DAI Pin Routing

Parameter		Min	Max	Unit
Switching Characteristic				
t_{DPIO}	Delay DAI Pin Input Valid to DAI Output Valid	1.5	12	ns

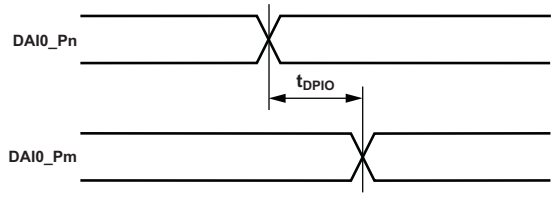

Figure 46. DAI Pin to DAI Pin Direct Routing

Up/Down Counter/Rotary Encoder Timing

Table 76 and Figure 47 describe timing, related to the general-purpose counter (CNT).

Table 76. Up/Down Counter/Rotary Encoder Timing

Parameter		Min	Max	Unit
Timing Requirement				
t_{WCOUNT}	Up/Down Counter/Rotary Encoder Input Pulse Width	$2 \times t_{SCLK0}$		ns

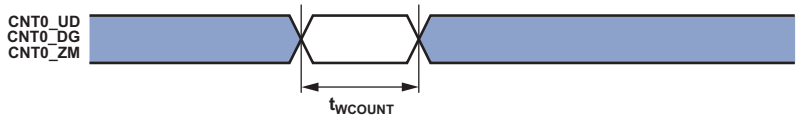

Figure 47. Up/Down Counter/Rotary Encoder Timing

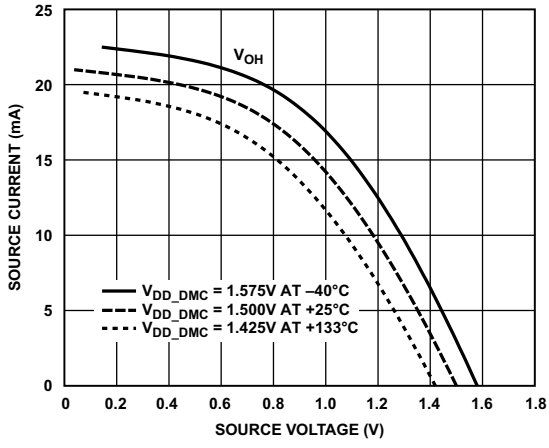

Figure 73. Driver Type B and Driver Type C (DDR3 Drive Strength 40 Ω)

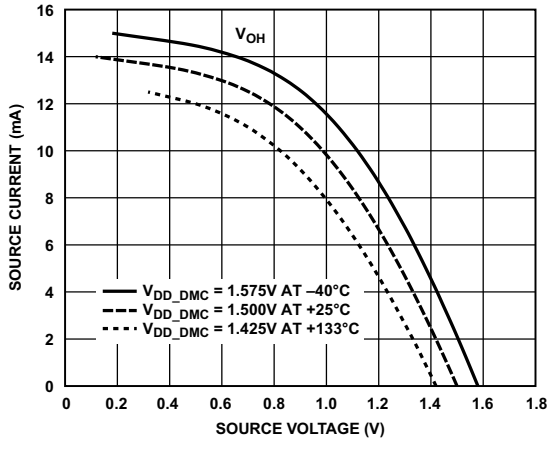

Figure 74. Driver Type B and Driver Type C (DDR3 Drive Strength 60 Ω)

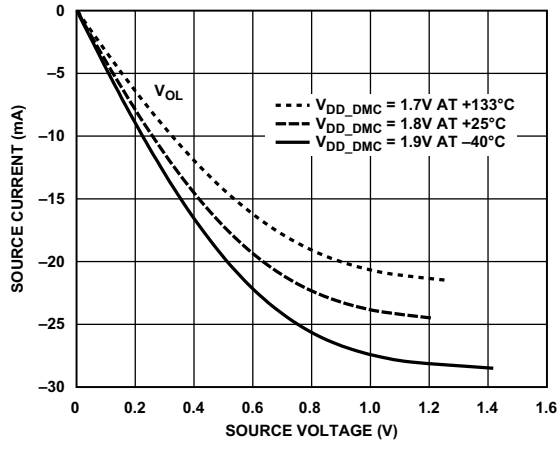

Figure 75. Driver Type B and Driver Type C (DDR2 Drive Strength 40 Ω)

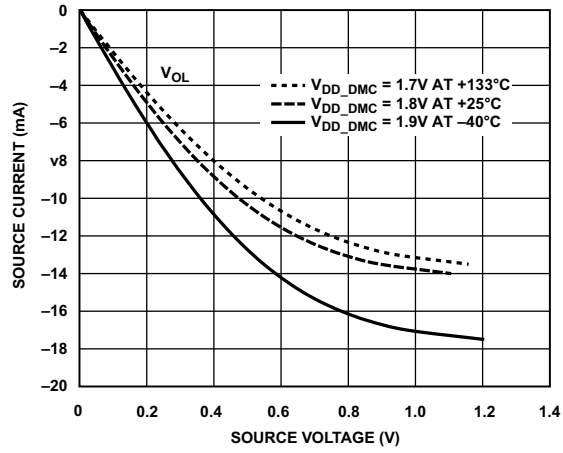

Figure 76. Driver Type B and Driver Type C (DDR2 Drive Strength 60 Ω)

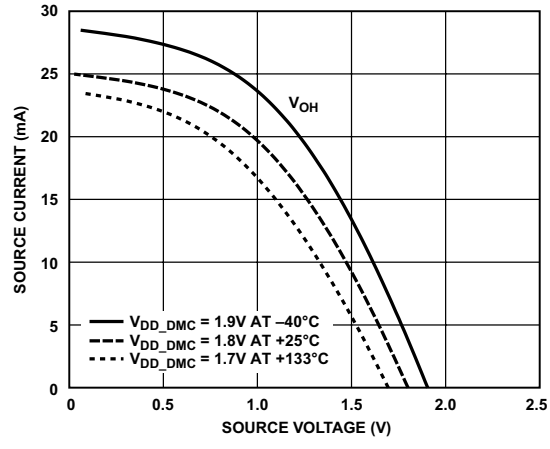

Figure 77. Driver Type B and Driver Type C (DDR2 Drive Strength 40 Ω)

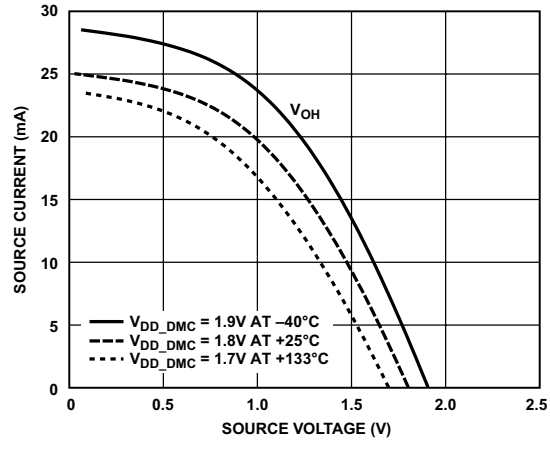

Figure 78. Driver Type B and Driver Type C (DDR2 Drive Strength 60 Ω)

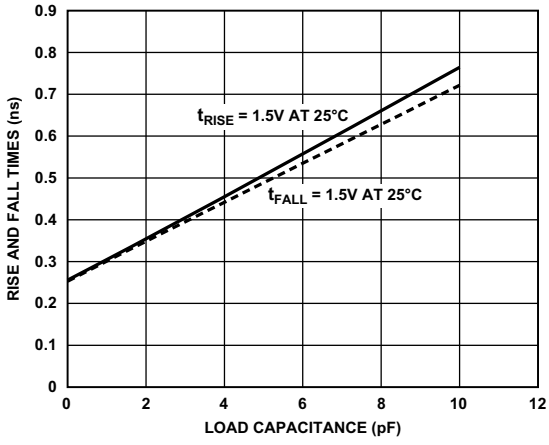

Figure 88. Driver Type B and Driver Type C Typical Rise and Fall Times (10% to 90%) vs. Load Capacitance (V_{DD_DMC} = 1.5 V) for DDR3

ENVIRONMENTAL CONDITIONS

To determine the junction temperature on the application PCB, use the following equation:

$$T_J = T_{CASE} + (\Psi_{JT} \times P_D)$$

where:
T_J = junction temperature (°C).
T_{CASE} = case temperature (°C) measured at the top center of the package.
Ψ_{JT} = from Table 96 and Table 97.
P_D = power dissipation (see the Total Internal Power Dissipation section for the method to calculate P_D).

Values of θ_{JA} are provided for package comparison and PCB design considerations. θ_{JA} can be used for a first order approximation of T_J by the following equation:

$$T_J = T_A + (\theta_{JA} \times P_D)$$

where T_A = ambient temperature (°C).

Values of θ_{JC} are provided for package comparison and PCB design considerations when an external heat sink is required.

In Table 96 and Table 97, airflow measurements comply with JEDEC standards JESD51-2 and JESD51-6. The junction to case measurement complies with MIL-STD-883 (Method 1012.1). All measurements use a 6 layer PCB with 101.6 mm × 152.4 mm dimensions.

Table 96. Thermal Characteristics for 400 CSP_BGA

Parameter	Conditions	Typical	Unit
θ_{JA}	0 linear m/s air flow	14.24	°C/W
θ_{JA}	1 linear m/s air flow	12.61	°C/W
θ_{JA}	2 linear m/s air flow	12.09	°C/W
θ_{JC}		5.71	°C/W
Ψ_{JT}	0 linear m/s air flow	0.08	°C/W
Ψ_{JT}	1 linear m/s air flow	0.14	°C/W
Ψ_{JT}	2 linear m/s air flow	0.17	°C/W

Table 97. Thermal Characteristics for 176 LQFP_EP

Parameter	Conditions	Typical	Unit
θ_{JA}	0 linear m/s air flow	11.95	°C/W
θ_{JA}	1 linear m/s air flow	10.43	°C/W
θ_{JA}	2 linear m/s air flow	9.98	°C/W
θ_{JC}		11.10	°C/W
Ψ_{JT}	0 linear m/s air flow	0.15	°C/W
Ψ_{JT}	1 linear m/s air flow	0.24	°C/W
Ψ_{JT}	2 linear m/s air flow	0.29	°C/W

ADSP-SC57x/ADSP-2157x 400-BALL BGA BALL ASSIGNMENTS

The ADSP-SC57x/ADSP-2157x 400-Ball BGA Ball Assignments (Numerical by Ball Number) table lists the 400-ball BGA package by ball number.

The ADSP-SC57x/ADSP-2157x 400-Ball BGA Ball Assignments (Alphabetical by Pin Name) table lists the 400-ball BGA package by pin name.

ADSP-SC57x/ADSP-2157x 400-BALL BGA BALL ASSIGNMENTS (NUMERICAL BY BALL NUMBER)

Ball No.	Pin Name	Ball No.	Pin Name	Ball No.	Pin Name	Ball No.	Pin Name
A01	GND	C02	PC_13	E03	PE_03	G04	VDD_EXT
A02	PA_10	C03	GND	E04	PE_02	G05	VDD_INT
A03	PA_09	C04	PA_12	E05	GND	G06	GND
A04	PA_11	C05	PA_14	E06	PB_00	G07	GND
A05	PE_07	C06	PB_03	E07	VDD_EXT	G08	GND
A06	MLB0_CLKN	C07	PB_02	E08	VDD_EXT	G09	GND
A07	MLB0_CLKP	C08	PE_10	E09	VDD_EXT	G10	GND
A08	MLB0_SIGN	C09	PB_06	E10	VDD_EXT	G11	GND
A09	GND	C10	PB_05	E11	VDD_EXT	G12	GND
A10	SYS_XTAL0	C11	$\overline{\text{SYS\_HWRST}}$	E12	VDD_EXT	G13	GND
A11	SYS_CLKIN0	C12	USB0_ID	E13	VDD_USB	G14	GND
A12	GND	C13	USB0_CLKIN	E14	JTG_TCK	G15	GND
A13	SYS_XTAL1	C14	PB_12	E15	PE_15	G16	VDD_INT
A14	SYS_CLKIN1	C15	PB_13	E16	GND	G17	PB_15
A15	GND	C16	JTG_TDI	E17	VDD_EXT	G18	DAI0_PIN08
A16	USB0_DP	C17	PE_14	E18	PF_04	G19	DAI0_PIN10
A17	USB0_DM	C18	GND	E19	DAI0_PIN07	G20	DAI0_PIN09
A18	PF_03	C19	PF_08	E20	DAI0_PIN03	H01	PE_01
A19	PF_05	C20	PF_11	F01	PC_02	H02	PC_09
A20	GND	D01	PC_06	F02	PC_03	H03	PC_15
B01	PC_12	D02	PC_08	F03	PC_04	H04	VDD_EXT
B02	GND	D03	PE_04	F04	PE_06	H05	VDD_INT
B03	PA_13	D04	GND	F05	VDD_INT	H06	GND
B04	PA_15	D05	PE_08	F06	GND	H07	GND
B05	PB_01	D06	PE_11	F07	VDD_INT	H08	GND
B06	PB_04	D07	PE_09	F08	VDD_INT	H09	GND
B07	MLB0_DATN	D08	PB_08	F09	VDD_INT	H10	GND
B08	MLB0_DATP	D09	PB_07	F10	VDD_INT	H11	GND
B09	MLB0_SIGP	D10	PB_09	F11	VDD_INT	H12	GND
B10	$\overline{\text{JTG\_TRST}}$	D11	SYS_CLKOUT	F12	VDD_INT	H13	GND
B11	USB0_VBUS	D12	PB_11	F13	VDD_INT	H14	GND
B12	USB0_XTAL	D13	USB0_VBC	F14	VDD_INT	H15	GND
B13	PB_10	D14	PB_14	F15	GND	H16	VDD_INT
B14	JTG_TDO	D15	PE_13	F16	VDD_INT	H17	VDD_EXT
B15	JTG_TMS	D16	PE_12	F17	PF_02	H18	DAI0_PIN05
B16	PF_00	D17	GND	F18	PF_09	H19	DAI0_PIN14
B17	PF_01	D18	PF_10	F19	DAI0_PIN02	H20	DAI0_PIN11
B18	PF_06	D19	DAI0_PIN01	F20	DAI0_PIN06	J01	PE_00
B19	GND	D20	DAI0_PIN04	G01	PC_00	J02	PC_07
B20	PF_07	E01	PC_05	G02	PC_14	J03	PC_10
C01	PC_11	E02	PE_05	G03	PC_01	J04	VDD_EXT

Pin Name	Ball No.
VDD_INT	L16
VDD_INT	M05
VDD_INT	M16
VDD_INT	N05
VDD_INT	N16
VDD_INT	P05
VDD_INT	P06
VDD_INT	P08
VDD_INT	P09
VDD_INT	P10
VDD_INT	P11
VDD_INT	P12
VDD_INT	P13
VDD_INT	P15
VDD_INT	P16
VDD_INT	R04
VDD_INT	R05
VDD_INT	R07
VDD_INT	R08
VDD_INT	R09
VDD_INT	R10
VDD_INT	R11
VDD_INT	R12
VDD_INT	R13
VDD_INT	R14
VDD_INT	R16
VDD_INT	R17
VDD_USB	E13

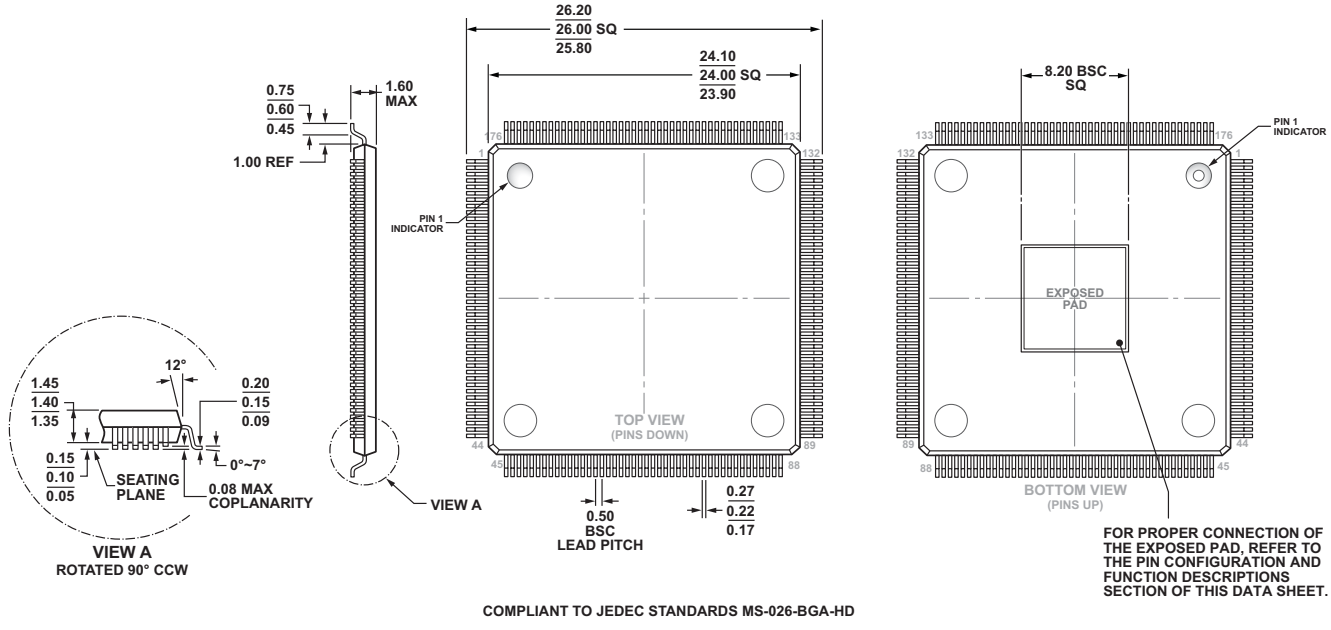

Figure 93. 176-Lead Low Profile Quad Flat Package, Exposed Pad [LQFP_EP]
(SW-176-5)
Dimensions shown in millimeters

SURFACE-MOUNT DESIGN

Table 98 is provided as an aid to PCB design. For industry-standard design recommendations, refer to IPC-7351, *Generic Requirements for Surface-Mount Design and Land Pattern Standard.*

Table 98. CSP_BGA Data for Use with Surface-Mount Design

Package	Package Ball Attach Type	Package Solder Mask Opening	Package Ball Pad Size
BC-400-2	Solder Mask Defined	0.4 mm Diameter	0.5 mm Diameter